

# GD54/74HC259, GD54/74HCT259

## 8-BIT ADDRESSABLE LATCH/3-TO-8 LINE DECODER

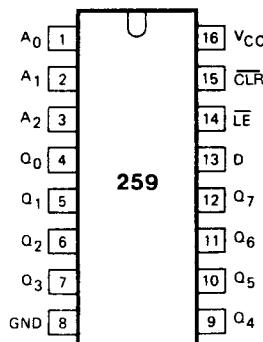
### General Description

These devices are identical in pinout to the 54/74LS259. This 8-Bit Addressable latch can perform four basic functions in the addressable latch mode, data is read into the addressed stage of the latch. In the memory mode, the latch contents are stored regardless of any other inputs. In the 8-line decoder mode, data flows through to the addressed output. And in the clear mode, all stages are cleared to the low state. To eliminate the possibility of entering erroneous data into the latches, the enable should be held high (inactive) while the address lines are changing.

### Features

- Low Power consumption characteristic of CMOS devices
- Output drive capability: 10 LS TTL Loads Min.
- Operating speed superior to LS TTL
- Wide operating voltage range: for HC 2 to 6 volts for HCT 4.5 to 5.5 volts
- Low input current: 1 $\mu$ A Max.
- Low quiescent current: 80 $\mu$ A Max. (74HC)
- High noise immunity characteristic of CMOS
- Diode protection on all inputs

### Pin Configuration



Suffix-Blank : Plastic Dual In Line Package  
Suffix-J : Ceramic Dual In Line Package  
Suffix-D : Small Outline Package

### Logic Diagram

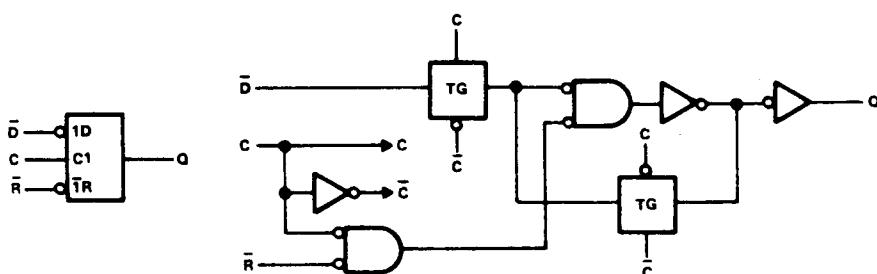


Fig. 1 Logic diagram (each latch)

## Function Table

OPERATING MODES	INPUTS								OUTPUTS							
	CLR	LE	D	A <sub>0</sub>	A <sub>1</sub>	A <sub>2</sub>	Q <sub>0</sub>	Q <sub>1</sub>	Q <sub>2</sub>	Q <sub>3</sub>	Q <sub>4</sub>	Q <sub>5</sub>	Q <sub>6</sub>	Q <sub>7</sub>		
master clear	L	H	X	X	X	X	L	L	L	L	L	L	L	L	L	L
demultiplex (active HIGH) decoder (when D = H)	L	L	d	L	L	L	Q=d	L	L	L	L	L	L	L	L	L
store (do nothing)	H	H	X	X	X	X	q <sub>0</sub>	q <sub>1</sub>	q <sub>2</sub>	q <sub>3</sub>	q <sub>4</sub>	q <sub>5</sub>	q <sub>6</sub>	q <sub>7</sub>		
addressable latch	H	L	d	L	L	L	Q=d	q <sub>1</sub>	q <sub>2</sub>	q <sub>3</sub>	q <sub>4</sub>	q <sub>5</sub>	q <sub>6</sub>	q <sub>7</sub>		
	H	L	d	H	L	L	q <sub>0</sub>	Q=d	q <sub>2</sub>	q <sub>3</sub>	q <sub>4</sub>	q <sub>5</sub>	q <sub>6</sub>	q <sub>7</sub>		
	H	L	d	L	H	L	q <sub>0</sub>	q <sub>1</sub>	Q=d	q <sub>3</sub>	q <sub>4</sub>	q <sub>5</sub>	q <sub>6</sub>	q <sub>7</sub>		
	H	L	d	H	L	H	q <sub>0</sub>	q <sub>1</sub>	q <sub>2</sub>	Q=d	q <sub>4</sub>	q <sub>5</sub>	q <sub>6</sub>	q <sub>7</sub>		
	H	L	d	L	H	H	q <sub>0</sub>	q <sub>1</sub>	q <sub>2</sub>	q <sub>3</sub>	Q=d	q <sub>5</sub>	q <sub>6</sub>	q <sub>7</sub>		
	H	L	d	H	H	H	q <sub>0</sub>	q <sub>1</sub>	q <sub>2</sub>	q <sub>3</sub>	q <sub>4</sub>	Q=d	q <sub>6</sub>	q <sub>7</sub>		

H = HIGH voltage level  
L = LOW voltage level  
X = don't care

d = HIGH or LOW data one set-up time prior to the LOW-to-HIGH LE transition

q = lower case letters indicate the state of the referenced output established during the last cycle in which it was addressed or cleared

## Logic Diagram

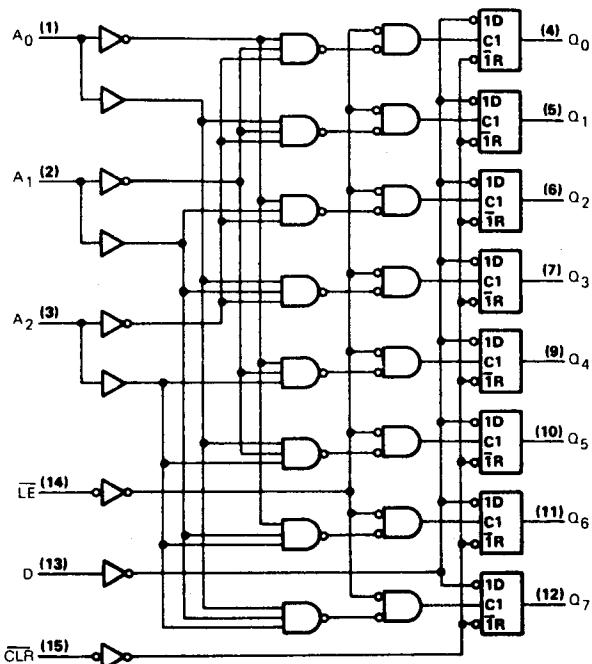


Fig. 2 Logic diagram

**Absolute Maximum Ratings**

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	DC Supply voltage		-0.5	+7	V
$I_{IK}, I_{OK}$	DC input or output diode current	for $V_i < -0.5$ or $V_i > V_{CC} + 0.5V$		$ 20 $	mA
$I_O$	DC output source or sink current	for $-0.5V < V_O < V_{CC} + 0.5V$		$ 25 $	mA
$I_{CC}$	DC $V_{CC}$ or GND current			$ 50 $	mA
$T_{STG}$	Storage temperature range		-65	150	°C
$P_D$	Power dissipation per package	above $+70^{\circ}\text{C}$ : derate linearly with 8mW/K		500	mW
$T_L$	Lead temperature	At distance $1/16 \pm 1/32$ in. from case for 60 sec(CERAMIC) 10 sec(PLASTIC)		300 260	°C

**Recommended Operating Conditions**

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range $V_{CC}$ : GD54/74HC Types GD54/74HCT Types	2 4.5	6 5.5	V
DC Input or Output Voltage $V_i, V_O$	0	$V_{CC}$	V
Operating Temperature $T_A$ : GD74 Types GD54 Types	-40 -55	+85 +125	°C
Input Rise and Fall times $t_r, t_f$ : GD54/74HC Types at 2V at 4.5V at 6V GD54/74HCT Types at 4.5V		1000 500 400 500	ns

## DC Electrical Characteristics for HC

SYMBOL	PARAMETER	TEST CONDITION	V <sub>CC</sub> (V)	T <sub>A</sub> =25°C			GD74HC259		GD54HC259		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
V <sub>IH</sub>	HIGH level input Voltage		2.0 4.5 6.0	1.5 3.15 4.2			1.5 3.15 4.2		1.5 3.15 4.2		V
V <sub>IL</sub>	LOW level input voltage		2.0 4.5 6.0		0.3 0.9 1.2		0.3 0.9 1.2		0.3 0.9 1.2		V
V <sub>OH</sub>	HIGH level output voltage	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> =-20µA	2.0 4.5 6.0	1.9 4.4 5.9	2.0 4.5 6.0		1.9 4.4 5.9	1.9 4.4 5.9		V
			I <sub>OH</sub> =-4mA I <sub>OH</sub> =-5.2mA	4.5 6.0	3.98 5.48	4.3 5.2		3.84 5.34	3.7 5.2		
V <sub>OL</sub>	LOW level output voltage	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> =20µA	2.0 4.5 6.0		0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
			I <sub>OL</sub> =4mA I <sub>OL</sub> =5.2mA	4.5 6.0		0.17 0.15	0.26 0.26		0.33 0.33	0.4 0.4	
I <sub>IN</sub>	Input leakage Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	6.0			0.1		1.0		1.0	µA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> =V <sub>CC</sub> or GND I <sub>out</sub> =0µA	6.0			8		80		160	µA

## DC Electrical Characteristics for HCT

SYMBOL	PARAMETER	TEST CONDITION	V <sub>CC</sub> (V)	T <sub>A</sub> =25°C			GD74HCT259		GD54HCT259		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
V <sub>IH</sub>	HIGH level input Voltage		4.5 to 5.5	2.0			2.0		2.0		V
V <sub>IL</sub>	LOW level input voltage		4.5 to 5.5			0.8		0.8		0.8	V
V <sub>OH</sub>	HIGH level output voltage	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> =-20µA	4.5	4.4	4.5		4.4		4.4	V
			I <sub>OH</sub> =-4mA	4.5	3.98	4.3		3.84		3.7	
V <sub>OL</sub>	LOW level output voltage	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> =20µA	4.5		0.1		0.1		0.1	V
			I <sub>OL</sub> =4mA	4.5		0.17	0.26		0.33	0.4	
I <sub>IN</sub>	Input leakage Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	5.5			0.1		1.0		1.0	µA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> =V <sub>CC</sub> or GND I <sub>out</sub> =0µA	5.5			8		80		160	µA

**Timing Requirements for HC:  $t_r=t_f=6\text{ns}$   $C_L=50\text{ pF}$**

SYMBOL	PARAMETER	$V_{CC}$ (V)	$T_A=25^\circ\text{C}$			GD74HCT259		GD54HCT259		UNIT
			MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
$t_W$	Pulse width $\bar{LE}$ , $\bar{CLR}$ high or low	2.0	80	30		100		120		ns
		4.5	16	10		20		25		
		6.0	14	8		18		22		
$t_{SU}$	Setup time Data after $LE\downarrow$	2.0	60	30		100		120		ns
		4.5	12	10		20		25		
		6.0	10	8		18		22		
$t_h$	Hold time Data before $LE\downarrow$	2.0	3	0		3		3		ns
		4.5	3	0		3		3		
		6.0	3	0		3		3		

**AC Characteristics for HC:  $t_r=t_f=6\text{ns}$   $C_L=50\text{ pF}$**

SYMBOL	PARAMETER	$V_{CC}$ (V)	$T_A=25^\circ\text{C}$			GD74HCT259		GD54HCT259		UNIT
			MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
$t_{PLH}/$ $t_{PHL}$	Propagation Delay Time $D$ to $Q_n$	2.0		50	160		210		260	ns
		4.5		18	35		42		50	
		6.0		17	30		38		46	
$t_{PLH}/$ $t_{PHL}$	Propagation Delay Time $A_n$ to $Q_n$	2.0		50	160		210		260	ns
		4.5		18	35		42		50	
		6.0		17	30		38		46	
$t_{PLH}/$ $t_{PHL}$	Propagation Delay Time $\bar{LE}$ to $Q_n$	2.0		48	150		200		250	ns
		4.5		17	33		40		48	
		6.0		16	28		36		42	
$t_{PHL}$	Propagation Delay Time $\bar{CLR}$ to $Q_n$	2.0		48	150		200		250	ns
		4.5		17	32		40		48	
		6.0		16	28		36		42	
$t_{TLH}/$ $t_{THL}$	Output Transition Time	2.0		25	70		85		100	ns
		4.5		8	15		18		22	
		6.0		7	13		16		19	

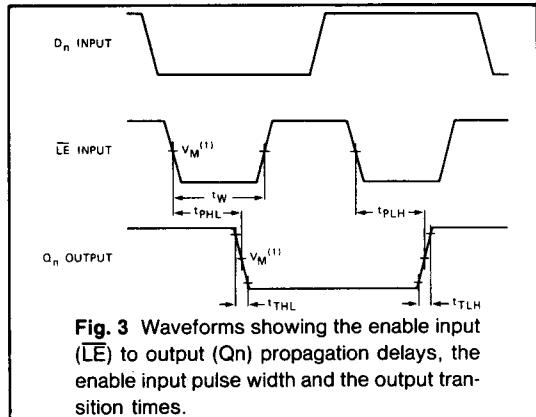
**Timing Requirements for HCT:  $t_r=t_f=6\text{ ns}$   $C_L=50\text{ pF}$** 

SYMBOL	PARAMETER	$V_{CC}$ (V)	$T_A=25^\circ C$			GD74HCT259		GD54HCT259		UNIT
			MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
$t_w$	Pulse width $\overline{LE}$ , $\overline{CLR}$ high or low	4.5	16	10		20		25		ns
$t_{SU}$	Setup time Data after $\overline{LE} \downarrow$	4.5	12	10		20		25		ns
$t_h$	Hold time Data before $\overline{LE} \downarrow$	4.5	3	0		3		3		ns

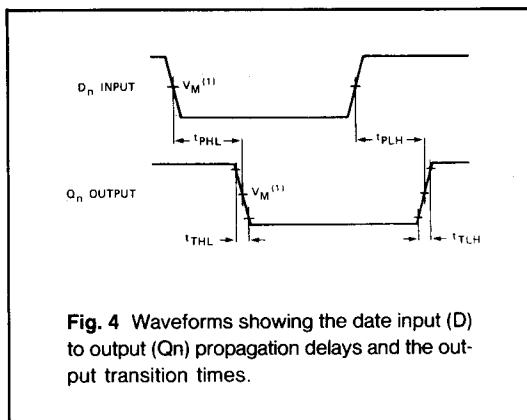
**AC Characteristics for HCT:  $t_r=t_f=6\text{ ns}$   $C_L=50\text{ pF}$** 

SYMBOL	PARAMETER	$V_{CC}$ (V)	$T_A=25^\circ C$			GD74HCT259		GD54HCT259		UNIT
			MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
$t_{PLH}$ $t_{PHL}$	Propagation Delay Time D to Qn	4.5		20	38		46		55	ns
$t_{PLH}/$ $t_{PHL}$	Propagation Delay Time An to Qn	4.5		20	38		46		55	ns
$t_{PLH}/$ $t_{PHL}$	Propagation Delay Time $\overline{LE}$ to Qn	4.5		19	36		44		52	ns
$t_{PHL}$	Propagation Delay Time $\overline{CLR}$ to Qn	4.5		19	36		44		52	ns
$t_{TLH}/$ $t_{THL}$	Output Transition Time	4.5		8	15		18		22	ns

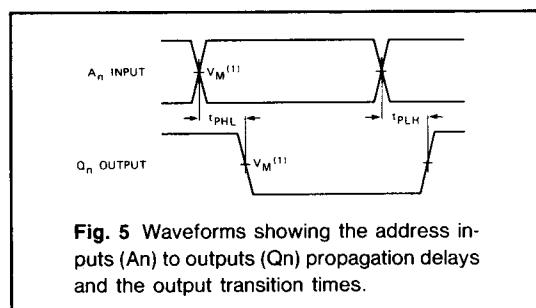
## AC Waveforms



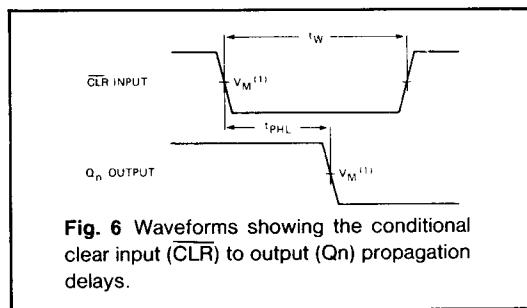
**Fig. 3** Waveforms showing the enable input (LE) to output (Qn) propagation delays, the enable input pulse width and the output transition times.



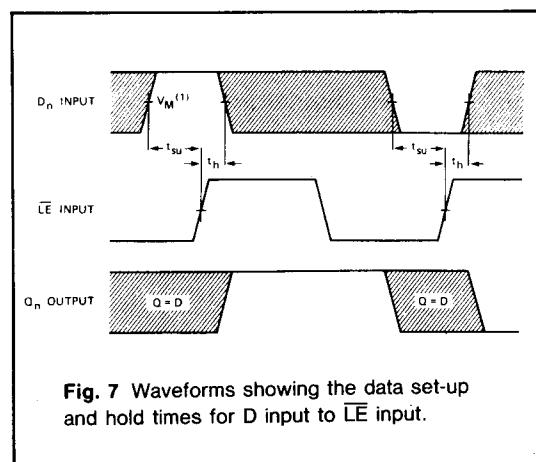
**Fig. 4** Waveforms showing the date input (D) to output (Qn) propagation delays and the output transition times.



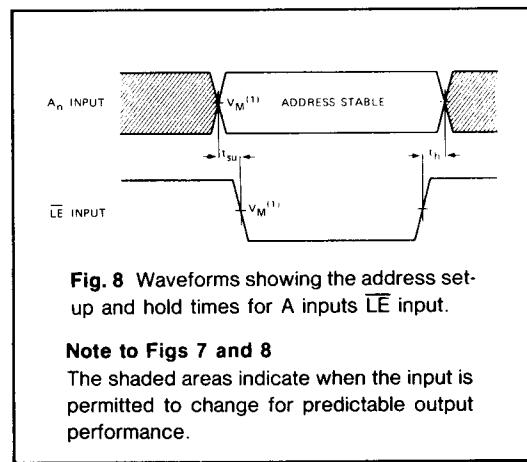
**Fig. 5** Waveforms showing the address inputs (An) to outputs (Qn) propagation delays and the output transition times.



**Fig. 6** Waveforms showing the conditional clear input (CLR) to output (Qn) propagation delays.



**Fig. 7** Waveforms showing the data set-up and hold times for D input to LE input.



**Fig. 8** Waveforms showing the address set-up and hold times for A inputs LE input.

### Note to Figs 7 and 8

The shaded areas indicate when the input is permitted to change for predictable output performance.

### Note to AC waveforms

- (1) HC :  $V_M = 50\%$ ;  $V_i = \text{GND}$  to  $V_{CC}$ .
- HCT :  $V_M = 1.3V$ ;  $V_i = \text{GND}$  to  $3V$ .